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10-4-02

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Charles A. MILLER

Art Unit: 3729

Application No: 09/819,181

Examiner:
Rick K. Chang

Filed: March 27, 2001

For: METHOD FOR FABRICATING AN IC
INTERCONNECT SYSTEM INCLUDING AN IN-
STREET INTEGRATED CIRCUIT WAFER VIAREPLY TO THE OFFICE ACTION MAILED 09/17/2002Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Further examination and consideration of this application are requested in view of the following Remarks.

REMARKS

The Examiner has indicated that the reply filed June 24, 2002 was not fully responsive to the prior Office Action because "claims are drawn to a semiconductor wafer". Per telephone conference with the Examiner on October 1, 2002, the Examiner indicated to the undersigned that the reply would be considered responsive if the applicant were to indicate where the term "semiconductor wafer" appears in the claims or specification as filed.

The term "semiconductor wafer" appeared in the preamble of 13 as originally filed, and the term "wafer" appearing in the body of claim 13 as originally filed referred to the "semiconductor wafer" recited in the preamble. The term "semiconductor wafer" also appeared in amended claims 15, 16, 17 and 18 as originally filed. Thus all amended claims 13-18 as originally filed recited a "semiconductor wafer."

The use of the term "semiconductor wafer" in claim 13 is also supported by the following sections of the specification as originally filed:

Smith-Hill and Bedell, P.C.

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FACSIMILE COVER SHEET

To: Rick K. Chang
Art Unit 3729

From: Daniel J. Bedell

Firm: US PATENT AND
TRADEMARK OFFICE

Date: October 1, 2002

Fax: 1-703-872-9302

Our ref: FORM 2132 (P129-US)

Your ref: 09/819,181

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